

REMARKS

The Office Action notes that claims 1-23 are pending in the application. Of these, claims 14-20 are withdrawn from consideration subject to an earlier Restriction Requirement. Claims 21 and 22 are allowed, and claims 1-13 and 23 are rejected. This Response introduces amendments to claim 1. The amendments are formal in nature therefore no new matter has been added. Claims 1-13 and 21-23 remain under consideration.

Claim 1 stands rejected under 35 USC § 112, first paragraph is failing to comply with the written description requirement. Specifically, the Examiner objects that the thickness value of “at least equal to .04 microns” is not set forth in the specification. The Applicant respectfully requests that the Examiner review Figure 9 which clearly provides support for this limitation. If the Examiner requires, the Applicant would be willing to add a description of this to the Detailed Description using Figure 9 as support.

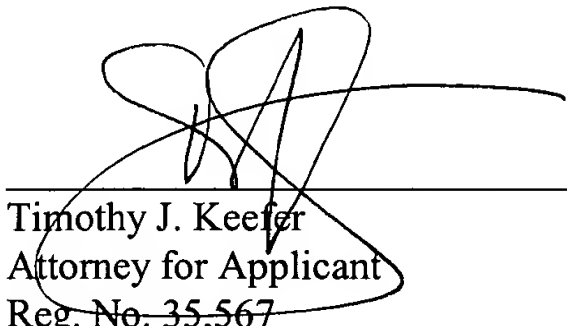
Claims 1-8, 10 and 12-13 stand rejected under 35 USC § 102(b) as being anticipated by, or in the alternative, as being obvious over Adair et al (U.S. Patent No. 5,504,877 “Adair”).

Claim 1 sets forth a method for producing a polymer/particle composite. The method includes the step of “forming a layer containing a polymeric material, wherein the layer has a thickness that is at least equal to .04 microns”. The Examiner sets forth column 4, lines 45-54 as teaching a polymeric layer having a thickness from .1 micron to 100 microns. The Applicant respectfully disagrees and requests the Examiner to review the cited column of Adair once again. The disclosure related to 1 to 100 microns does not refer to the thickness of a polymer layer but rather refers to the thickness of a diamond seed layer. Accordingly, the Applicant respectfully submits that Adair does not teach or suggest all of the elements of claim 1.

In view of aforesaid, the Applicant respectfully submits that the present application is in consideration for allowance. Favorable reconsideration is requested.

Respectfully submitted,

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Signed: 

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